Fein Focus Series FXS 100.23
Real Time X-Ray Imaging System

DESCRIPTION:
• Used for observing semiconductor bonds, bare board registration of inner layers, populated PWB solder joints, ceramic material flaws, etc.
• Non-contact, non-destructive inspection
• Integrated X-Y-Z manipulation system
• Tilt and rotate control
• Real-time video imaging
• Magnification zoom of 2X up to 180X (depending on the thickness and orientation of the sample)
• Maximum sample size 12”x15”
• Voiding calculation & BGA inspection software.

LOCATION: IEEC RELIABILITY LAB

For more information or to arrange for the use of this equipment, contact any of the IEEC staff members listed below:

Bill Infantolino
(607)777-4349
binfanto@binghamton.edu

Steve Cain
(607)777-5467
scain@binghamton.edu

Ron Kuracina
(607) 777-4334
kuracina@binghamton.edu